

What is claimed is ;

1. A bonding pad structure for improving impedance matching, which
is used in an electronic device having multiple electrical-connected
5 layers for signal transmission and grounding, comprising:

at least two bonding pads, that is neighbored to each other, wherein,
the two bonding pads respectively comprises at least two metal
layers and at least two plugs that are successively superimposed
10 to one another, further, the two neighboring bonding pads
respectively should have at least a metal layer parallel extending
toward its neighboring bonding pad, and superimposing a portion
of the other metal layer of its neighboring bonding pad to form an
additional capacitor.

2. The bonding pad structure of claim 1, wherein the electronic device
15 is a chip.

3. The bonding pad structure of claim 1, wherein the electronic device
is a printed circuit board.

4. The bonding pad structure of claim 2, wherein the chip comprises
six metal layers.

20 5. The bonding pad structure of claim 4, wherein the bonding pad
structure comprises three bonding pads, that respectively are a first
bonding pad, a second bonding pad, and a third bonding pad.

6. The bonding pad structure of claim 5, wherein the first bonding pad,
the second bonding pad, and the third bonding pad comprise
25 respectively three plugs and three metal layers, in addition, on one
side of the second bonding pad, the metal layers parallel extending
toward one another that are successively overlapping one another
from top to bottom are: the first metal layer of the first bonding pad,
the second metal layer of the second bonding pad, the second metal
layer of the first bonding pad, the third metal layer of the second
30 bonding pad, the third metal layer of the first bonding pad,
furthermore, similarly on the other side of the second bonding pad,

the metal layers from top to bottom are: the first metal layer of the third bonding pad, the second metal layer of the second bonding pad, the second metal layer of the third bonding pad, the third metal layer of the second bonding pad, the third metal plate of the third bonding pad.

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7. A bonding pad structure for improving impedance matching, which is used in an electronic device having multiple electrical-connected layers for signal transmission and grounding, wherein, the feature of the bonding pad structure is as following: the space between two bonding pads of the bonding pad structure exists a metal structure constructed using a plurality of parallel-positioned metal plates which are overlapping and disconnected to one another

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8. The bonding pad structure of claim 7, wherein the two bonding pads is neighbored to each other and is buried inside the electronic component from the surface thereof into a depth of its interior, moreover, the two bonding pads respectively comprise, successively from the electronic component's surface to the interior thereof, a plurality of metal plates and a plurality of plugs that are successively superimposed to one another, in addition, the amount and the order of the plates and the plugs are depended on a designing requirement, wherein, the two neighboring bonding pads respectively should have at least a metal plate parallel extending toward its neighboring bonding pad, and superimposing a portion of the other metal plate of its neighboring bonding pad, also the two metal plates is positioned apart from each other with a distance.

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